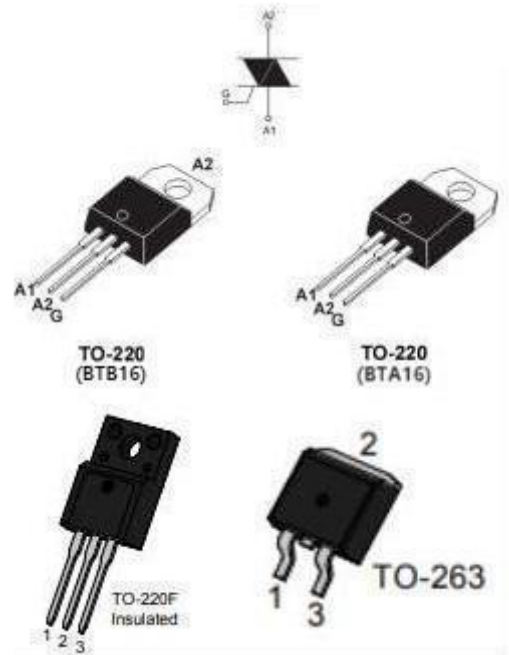


Product features and main applications:

NPNPN five-layer structure of silicon bidirectional devices; with independent intellectual property rights of single-sided digging technology, table glass passivation process; multi-layer metallized electrodes on the back; with high blocking voltage and high temperature stability.

Mainly used in:

vacuum cleaners, power tools and other motor speed controllers; solid state relays; heating controllers (temperature regulation); other phase control circuits.



Characteristics

Table 1. Absolute maximum ratings (Tj = 25 ° C unless otherwise stated)

Symbol	Parameter name		value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)	BTA BTB	Tc=80°C Tc=90°C	16 A
I_{TSM}	Non repetitive surge peak on-state current (full cycle, Tj initial = 25 ° C)	F=50HZ tp=20ms		160 A
I^2t	I2t value for fusing	tp=10ms		144 A ² S
di/dt	Critical rate of rise of on-state current IG = 2 x IGT, tr ≤ 100 ns	Tj=125°C		50 A/us

V_{DRM}/V_{RRM}	Off state repetitive peak voltage Reverse repetitive peak voltage	$T_j=25^{\circ}\text{C}$		600/800	V
I_{GM}	Peak gate current	$t_p=20\mu\text{s}$	$T_j=150^{\circ}\text{C}$	4	A
$P_{G(AV)}$	Average gate power dissipation		$T_j=150^{\circ}\text{C}$	1	W
T_{stg} T_j	Storage junction temperature range Operating junction temperature range			-40to+150 -40to+150	$^{\circ}\text{C}$

**Table 2. Electrical characteristics ($T_j = 25^{\circ}\text{C}$, unless otherwise specified) --
3 quadrants**

Symbol	Name and test conditions	Quadrant	Range	value			Unit
				Min	Typ	Max	
I_{GT}	$V_D=12\text{V}$ $R_L=100\Omega$	I II III		15	25	35	mA
V_{GT}			MAX	1.5			V
V_{GD}	$V_D = V_{DRM}$, $R_L = 3.3\text{ k}\Omega$, $T_j = 125^{\circ}\text{C}$		MIN	0.2			V
I_H	$I_T = 100\text{ mA}$		MAX	60			mA
I_L	$I_G = 1.2 \times I_{GT}$		MAX	I -III	60		mA
				II	100		
dv/dt	$V_D = 67\% V_{DRM}$, gate open, $T_j = 125^{\circ}\text{C}$		MIN	500			V/us
(dv/dt) _c	Critical rise rate of commutation voltage $T_j = 150^{\circ}\text{C}$		MIN	10			V/us

Table 3. Electrical characteristics ($T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified) - Standard Triac (4 quadrants)

Symbol	Name and test conditions	Quadrant	Range	value				Unit
I_{GT}	$V_D=12V$ $R_L=100\ \Omega$	I II III IV	MAX	I	II	III	IV	mA
				≤ 25	≤ 35	≤ 35	≤ 120	
V_{GT}	MAX		1.5				V	
V_{GD}	MIN		0.2				V	
I_H	$I_T=500\text{mA}$		MAX	60				mA
I_L	$I_G = 1.2 \times I_{GT}$		MAX	60				mA
				100				
dv/dt	$V_D = 67\% V_{DRM}$, gate open, $T_j = 125\text{ }^\circ\text{C}$		MIN	500				V/us
(dv/dt)c	Critical rise rate of commutation voltage $T_J = 150\text{ }^\circ\text{C}$		MIN	10				V/us

Static parameters

Symbol	Parameter name			value	Unit
V_{TM}	$I_{TM}= 32A$	$T_j=25^\circ\text{C}$	MAX	1.50	V
V_{T0}	threshold on-state voltage	$T_j=150^\circ\text{C}$	MAX	0.87	V
R_d	Dynamic resistance	$T_j=150^\circ\text{C}$	MAX	14.6	m Ω
I_{DRM} I_{RRM}	$V_{DRM} = V_{RRM}$	$T_j=25^\circ\text{C}$	MAX	5	μA
		$T_j=150^\circ\text{C}$		1	mA
$R_{th(j-c)}$	Junction to ambient	BTA		2.10	$^\circ\text{C/W}$
		BTB		1.30	

BTA16、BTB16 characteristic curve

FIG.1 Maximum power dissipation versus RMS on-state current

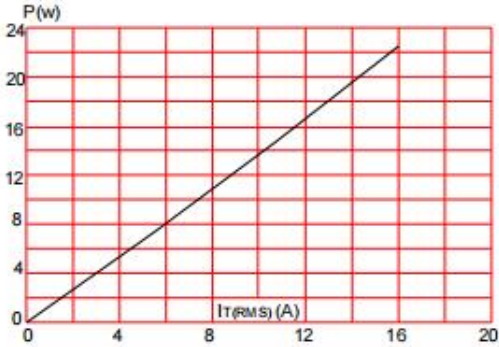


FIG.3: Surge peak on-state current versus number of cycles

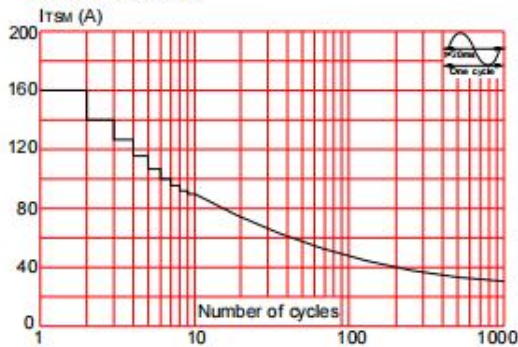


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20\text{ms}$, and corresponding value of I^2t ($di/dt < 50\text{A}/\mu\text{s}$)

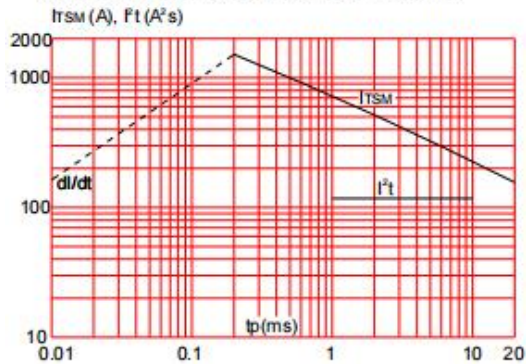


FIG.2: RMS on-state current versus case temperature

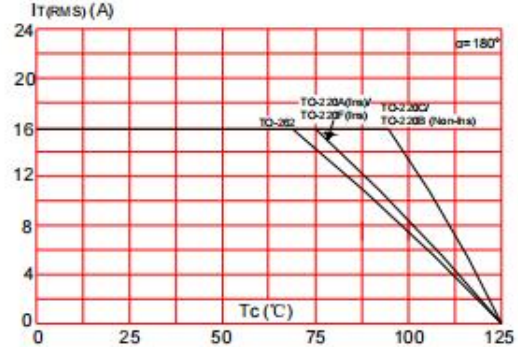


FIG.4: On-state characteristics (maximum values)

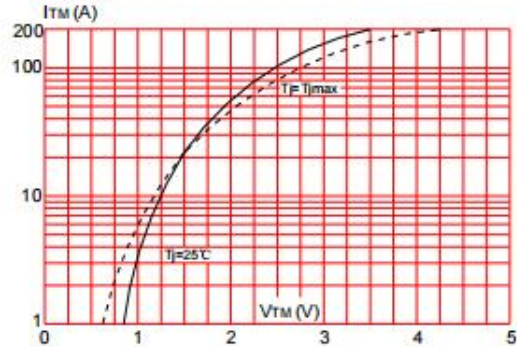
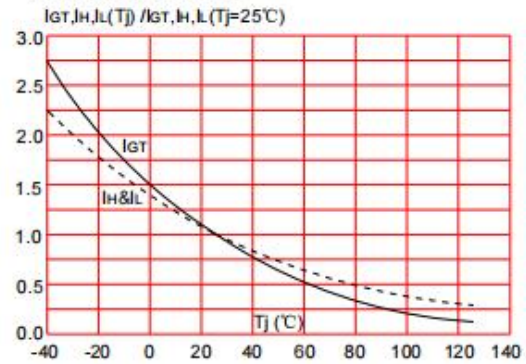
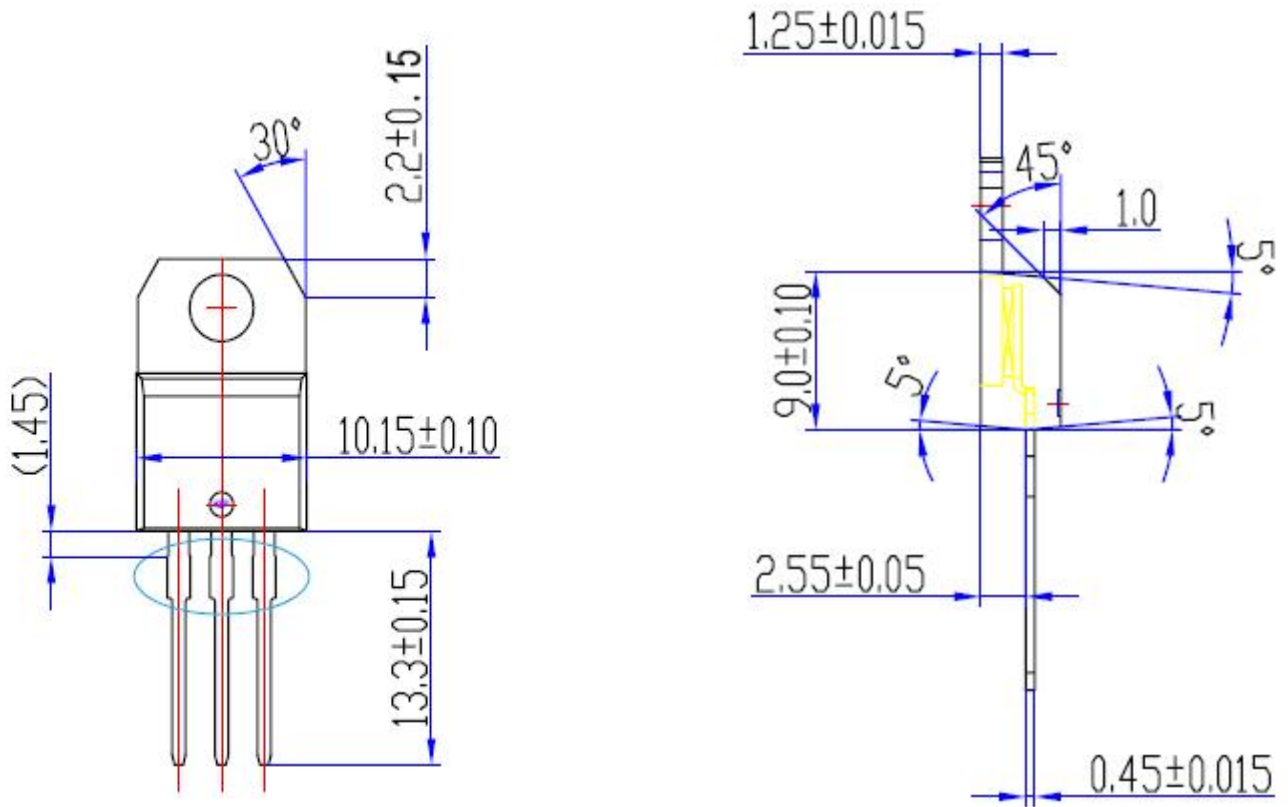


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature



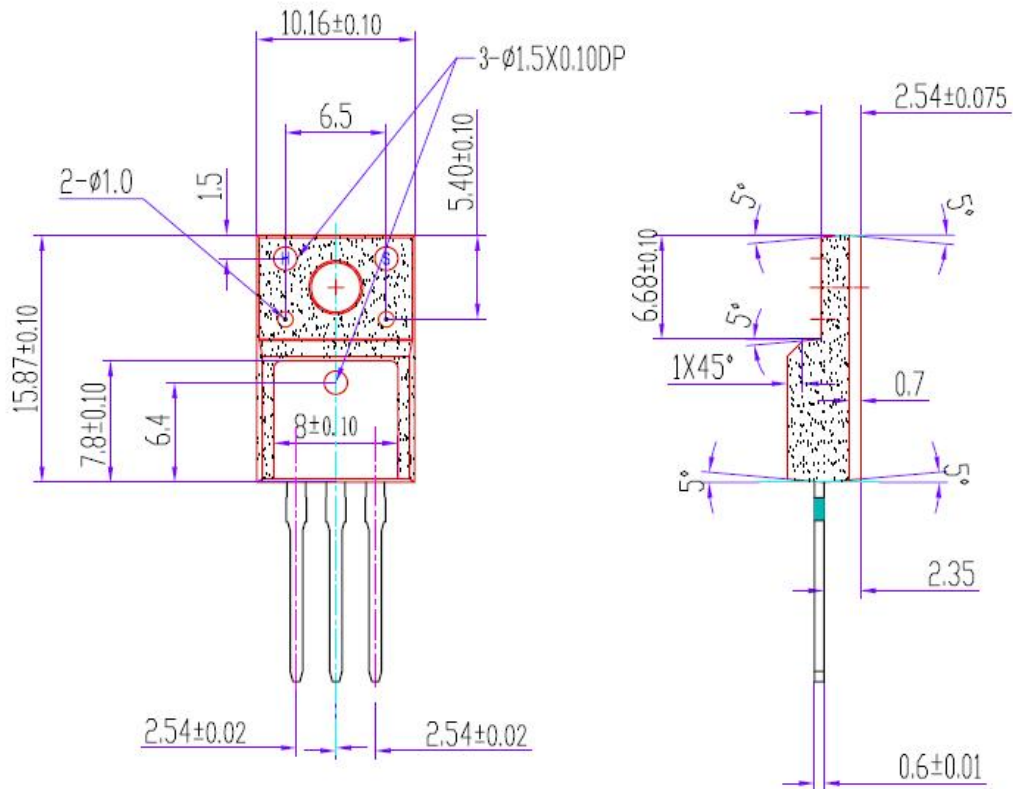
TO-220 Dimensional drawing:

Unit: mm (± 0.1)

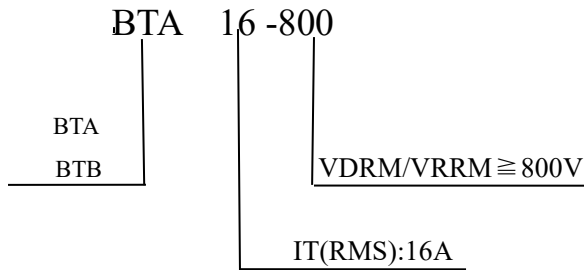


TO-220F Dimensional drawing:

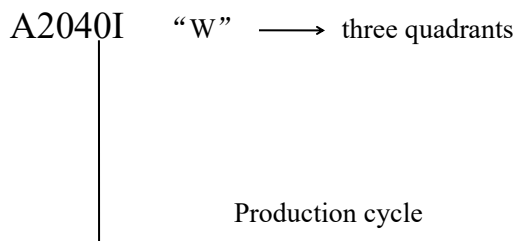
Unit: mm (± 0.1)



Product Marking Comments:



BTA: Insulation type
BTB: Non insulated type



XXXXX _____ Production batch number

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